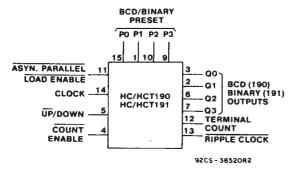
File Number 1662



Data sheet acquired from Harris Semiconductor SCHS275

### **High-Speed CMOS Logic**



#### **FUNCTIONAL DIAGRAM**

# Presettable Synchronous 4-Bit Up/Down Counters

CD54/74HC/HCT190 BCD Decade Counter CD54/74HC/HCT191 Binary Counter

#### Type Features:

- Synchronous counting and asynchronous loading
- Two outputs for n-bit cascading
- Look-ahead carry for high-speed counting

The RCA-CD54/74HC/HCT190/191 are asynchronously presettable BCD Decade and Binary Up/Down synchronous counters, respectively.

Presetting the counter to the number on preset data inputs (P0-P3) is accomplished by a Low asynchronous parallel load input ( $\overline{PL}$ ). Counting occurs when  $\overline{PL}$  is high, Count Enable ( $\overline{CE}$ ) is low, and the Up/Down ( $\overline{U/D}$ ) input is either low for up-counting or high for down-counting. The counter is incremented or decremented synchronously with the low-to-high transition of the clock.

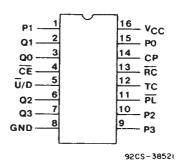
When an overflow or underflow of the counter occurs the Terminal Count output (TC), which is low during counting, goes high and remains high for one clock cycle. This output can be used for look-ahead carry in high-speed cascading (see Fig. 6). The TC output also initiates the Ripple Clock. (RC) output which, normally high, goes low and remains low for the low-level portion of the clock pulse. These counters can be cascaded using the Ripple Clock output as shown in Fig. 7.

If a decade counter is preset to an illegal state or assumes an illegal state when power is applied, it will return to the normal sequence in one or two counts as shown in state diagrams.

The CD54HC/HCT190 and the CD54HC/HCT191 are supplied in 16-lead ceramic dual-in-line packages (F suffix). The CD74HC/HCT190 and the CD74HC/HCT191 are supplied in a 16-lead dual-in-line plastic packages (E suffix) and in 16-lead dual-in-line surface mount plastic packages (M suffix). The CD54/74HC/HCT190 and the CD54/74HC/HCT191 are also supplied in chip form (H suffix).

Family Features:

- Fanout (Over Temperature Range): Standard Outputs - 10 LSTTL Loads Bus Driver Outputs - 15 LSTTL Loads
- Wide Operating Temperature Range: CD74HC/HCT: -40 to +85° C
- Balanced Propagation Delay and Transition Times
   Significant Power Reduction Compared to LSTTL
- Logic ICs
  Alternate Source is Philips/Signetics
- CD54HC/CD74HC Types: 2 to 6 V Operation High Noise Immunity: N<sub>IL</sub> = 30%, N<sub>IH</sub> = 30% of V<sub>CC</sub>, @ V<sub>CC</sub> = 5 V
- CD54HCT/CD74HCT Types: 4.5 to 5.5 V Operation Direct LSTTL Input Logic Compatibility V<sub>IL</sub> = 0.8 V Max., V<sub>IH</sub> = 2 V Min. CMOS Input Compatibility I<sub>I</sub> ≤ 1 μA @ V<sub>OL</sub>, V<sub>OH</sub>



HC/HCT190, HC/HCT191 TERMINAL ASSIGNMENT

This data sheet is applicable to the CD54HC190, CD74HC190, CD74HC190, CD54HC191, and CD54HC191. The CD54HCT190 was not acquired from Harris Semiconductor. See SCHS192 for information on the CD74HC191 and CD74HC191.

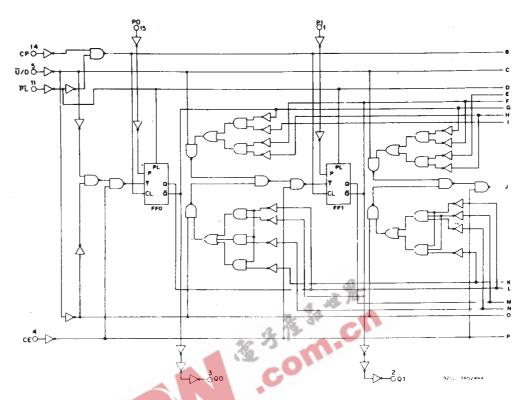


Fig. 1 - Logic diagram for HC/HCT190 (continued on next page).

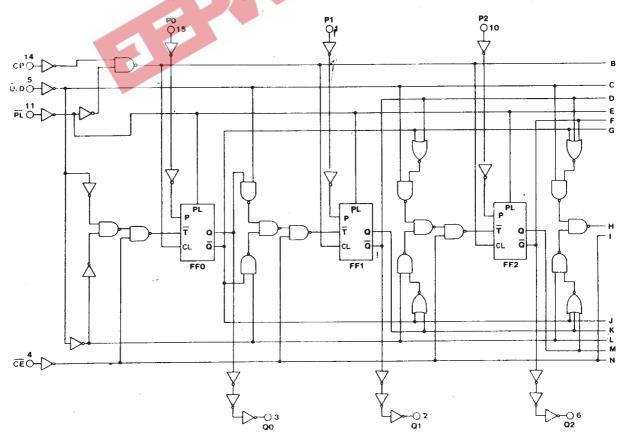


Fig. 2 - Logic diagram for HC/HCT191 (continued on next page).

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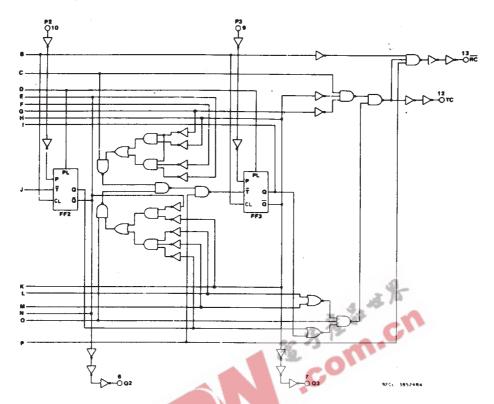


Fig. 1 - Logic diagram for HC/HCT190 (continued from previous page).

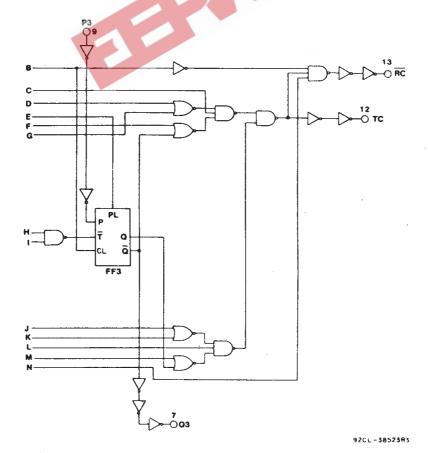
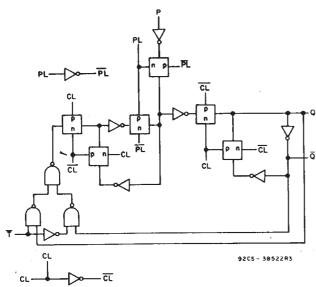


Fig. 2 - Logic diagram for HC/HCT191 (continued from previous page).



TRUTH TABLE

	Inp	uts		Function
PL	ĈE	U/D	CP	
Н	Ĺ	L	5	Count Up
н	L	Н		Count Down
L	×	X	Х	Asyn. Preset
Н	Н	х	х	No Change

#### Note:

Fig. 3 - Flip-flop cell for HC/HCT190 and HC/HCT191.

MUMIXAM	RATINGS,	Absolute-Maximum	Values:
	MOLTAGE !		

DC SUPPLY-VOLTAGE, (VCC).	-0.5 to +7 V
(Voltages referenced to ground)	
BC OUTPUT DIODE CHRRENT $I_{ov}$ (FOR $V_{o} < -0.5$ V OR $V_{o} > V_{oc} +0.5$	V) ±20 m/s
DO DDAIN CURRENT REPOLITRIT (In) (FOR -0.5 V < V-< V-> +0.5	V)
DC V <sub>CC</sub> OR GROUND CURRENT, (Icc)	IDU IIA
DOWER DISCIPATION REP PACKAGE (Pa):	F
For T <sub>A</sub> = -40 to +60°C (PACKAGE TYPE E)	
FORT - 460 to 495°C (PACKAGE TYPE F)	Derate Linearly at 8 mw/ C to 300 mw
FORT - 55 to +100°C (PACKAGE TYPE E H)	
For T <sub>2</sub> = +100 to +125°C (PACKAGE TYPE F. H)	Defate Linearly at 6 mw/ C to 500 mm
For T <sub>A</sub> = -40 to +70°C (PACKAGE TYPE M)	400 mw
For T <sub>A</sub> = +70 to +125°C (PACKAGE TYPE M)	Derate Linearly at 6 mW/° C to 70 mW
OPERATING-TEMPERATURE RANGE (TA):	
PACKAGE TYPE F, H.	
STORAGE TEMPERATURE (Tatg)	65 to +150°C
LEAD TEMPERATURE (DURING SOLDERING):	
At distance $1/16 \pm 1/32$ in. $(1.59 \pm 0.79 \text{ mm})$ from case for 10 s max.	+265°C
Unit inserted into a PC Board (min. thickness 1/16 in., 1.59 mm)	
with solder contacting lead tips only	+300°C

#### RECOMMENDED OPERATING CONDITIONS

For maximum reliability, nominal operating conditions should be selected so that operation is always within the following ranges:

	LIN	UNITS	
CHARACTERISTIC	MIN.	MAX.	011113
Supply-Voltage Range (For T <sub>A</sub> =Full Package Temperature Range)			
V <sub>cc</sub> :•			
CD54/74HC Types	2	6	l v
CD54/74HCT Types	4.5	5.5	<u> </u>
DC Input or Output Voltage, V <sub>I</sub> , V <sub>O</sub>	0	V <sub>cc</sub>	V
Operating Temperature, T <sub>A</sub> :			
CD74 Types	-40	+85	°C
CD54 Types	-55	+125	
Input Rise and Fall Times, t <sub>r</sub> t <sub>i</sub> :			
at 2 V	0	1000	
at 4.5 V	0	500	ns
at 6 V	0	400	

<sup>\*</sup>Unless otherwise specified, all voltages are referenced to Ground.

#### STATIC ELECTRICAL CHARACTERISTICS

					74HC 74HC									HCT							
		TEST CONDITIONS		1	i			IC PE	54F TY	-	TEST		74HC	T/54		74HCT TYPE		54HCT TYPE		UNITS	
CHARACTERISTI	C\$	V1 10 V		Vcc	,	25°C	25°C		-40/ +85° C		5/ 5°C	V <sub>1</sub> V <sub>∞</sub>			+25° C		-40/ +85°C		-55/ +125°C		
		v	mA	٧	Min	Тур	Max	Min	Max	Min	Max	٧	٧	Min	Тур	Mex	Min	Max	Min	n Max	
High-Level				2	1.5			1.5		1.5	_		4.5								
Input Voltage	VIH			4.5	3.15	<u>-</u>	_	3.15		3.15	_	_ '	to	2	_		2	-	2		V
				6	4.2		_	4.2	_	4.2			5.5								
Low-Level				2		_	0.5	_	0.5	_	0.5		4.5								
Input Voltage	V <sub>N</sub>			4.5		-	1.35	_	1.35	_	1.35	_	to	_	-	0.8	_	0.8	-	0.8	V
				6		_	1.8	_	1.8	_	1.8		5.5	_	<b>S</b>						
High-Level		VIL		2	1.9		_	1.9	_	1.9	_	ViL	3.	岭	110						
Output Voltage	VoH	or	-0.02	4.5	4.4	_	_	4.4	_	4.4	_	or	4.5	4.4	-	7	4.4	_	4.4	-	V
CMOS Loads		V <sub>III</sub>		6	5.9	_	_	5.9	_	5.9	_	Ver V	<b>7</b>		1						
		VIL								1	1	VIL	11	100							
TTL Loads		or	4	4.5	3.98	_	_	3.84		3.7	1	or	4.5	3.98	_	_	3.84	_	3.7	_	V
."		ViH	-5.2	6	5.48	_		5.34		5.2		VIH								1	
Low-Level		VIL		2	1_	_	0.1	4	0.1	17	0.1	Vıç									
Output Voltage	VoL	or	0.02	4.5		2	0.1		0.1	2	0.1	or	4.5	_	_	0.1	_	0.1	_	0.1	V
CMOS Loads	* OL	VIH	0.00	6	_		0.1	Z	0.1	_	0.1	ViH									
		VIL			7.1							Vit			_						
TTL Loads		or	4	4.5			0.26	-	0.33	_	0.4	or	4.5	_	_	0.26	_	0.33	_	0.4	v
I I L LOGUS		VIH	5.2	6		_	0.26	<del> </del>	0.33	_	0.4	V <sub>IH</sub>									
Input Leakage Current	l,	V <sub>cc</sub> or Gnd		6	_	_	±0.1		±1	_	±1	Any Voltage Between V <sub>cc</sub> and Gnd	5.5	_	_	±0.1		±1	_	±1	μΑ
Quiescent Device Current	lcc	V <sub>cc</sub> or Gnd	0	6	_	_	8		80	_	160	V <sub>cc</sub> or Gnd	5.5	_		8		80	_	160	μΑ
Additional Quiescent Device Current per Input Pin: 1 Unit Load	Δlcc*											Vcc -2.1	4.5 to 5.5	_	100	360	_	450		490	μΑ

<sup>\*</sup>For dual-supply systems theoretical worst case (V<sub>t</sub> = 2.4 V,  $V_{CC}$  = 5.5 V) specification is 1.8 mA.

#### **HCT Input Loading Table**

Input	Unit Loads*
P0-P3	0.4
CP	1.5
PL	1.5
Ū/D	1.2
CE	1.5

<sup>\*</sup>Unit load is  $\Delta$   $I_{CC}$  limit specified in Static Characteristics Chart, e.g., 360  $\mu A$  max. @ 25° C.

#### PREREQUISITE FOR SWITCHING FUNCTION

				25	°C		-4	0°C to	+85°	C	-55	5°C to	+125	°C_	-
CHARACTERISTIC	SYMBOL	Vcc	Н	c	н	СТ	741	нс	74H	ICT	54	нс	54H	СТ	UNITS
			Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	
Setup Time		2	60	_	_	_	75	_	_	_	90	<b>—</b>	_		
Pn to PL		4.5	12	_	12	-	15	_	15	–	18	_	18		
	·	6	10	_			13	_			15				
		2	60	_	_	-	75	<b>—</b>	-	—	90	-	_	-	
CE to CP	tsu	4.5	12	_	12	_	15	–	15	—	18	-	18		
		6	10				13	_			15				
		2	90	_	_	-	115	-	_	-	135	-	-	-	
Ū/D to CP		4.5	18	_	18	_	23	—	23	-	27	-	27	_	
		6	15	<u> </u>		<u> </u>	20		763	_	23	<u> </u>			
Hold Time		2	2	_	_	-	2		T.A.	_	2	-	-	<del></del> '	
Pn to PL		4.5	2	_	2		2	4	2	0	2	-	2	-	
		6	2			-4	2	-		M. T.	2		<u>  =</u>		ns
		2	2	_			2	3	_	-	2	-	-	-	
CE to CP	tн	4.5	2	-	2	-	2	_	2	-	2	-	2		
		6	2		1 -	-	2			_	2	<u>  -</u>	_	<u> </u>	
		2	0	7		-	0	-	-	-	0	-	-	-	
U/D to CP		4.5	0	1 -	0	-	0		0	-	0	-	0	-	
		6	0	_	_	_	0			<u> </u>	0	<u> </u>	<u>  -</u>	<u> </u>	
		2	6	_	-	-	5	-	-	-	4	-	-	-	
Maximum Frequency*	fmax	4.5	30	-	30	-	25	-	25	-	20	-	20	-	MH
•		6	35	_	_		29	<u> </u>		_	23_		_	<u>                                     </u>	
		2 :	60	_	T —	T	75	-	-	-	90	-	-	-	
Recovery Time	tREC	4.5	12	_	12	-	15	-	15	-	18	-	18	-	
•		6	10	_	_		13	<u> </u>	<u>                                     </u>	_	15	<u> </u>	<u> </u>	<u> </u>	1
		2	80	_	_	-	100	-		_	120	_	-	-	
CP Pulse Width	tw	4.5	16	_	16	_	20	_	20	-	24	-	24	-	ns
		6	14	_	_	_	17			<u> </u>	20			<u> </u>	
		2	100	1_		-	125	_		-	150	-	-	-	1
PL Pulse Width	tw	4.5	20	_	20	_	25	_	25	-	30	-	30	-	1
		6	17	_	_		21	1_		_	~26	_	l –	_	

<sup>\*</sup>Applies to non-cascaded operation only. With cascaded counters clock-to-terminal count propagation delays, count enable (CE)-to-clock set-up times, and count enable (CE)-to-clock hold times determine max. clock frequency. For example, with these HC devices:

$$f_{mex}$$
 (CP) =  $\frac{1}{\text{CP-to-TC prop. delay} + \overline{\text{CE}} - \text{to-CP setup} + \overline{\text{CE}} - \text{to-CP Hold}} = \frac{1}{42 + 12 + 2} \approx 18 \text{ MHz}$ 

SWITCHING CHARACTERISTICS (Vcc = 5 V, TA = 25°C, Input t,, t, = 6 ns)

			TYPICAL VALUES						
CHARACTERISTIC	SYMBOL	ŀ	łC	н	UNITS				
		190	191	190	191	]			
Propagation Delay (C <sub>L</sub> = 15 pF)									
PL to Qn		16	16	17	17				
Pn to Qn		14	14	16	16	]			
CP to Qn		14	14	14	14	]			
CP to RC	tpLH	10 10	11 1	11	ns				
CP to TC	tpHL	18	18	18	18	]			
U/D to RC		12	12	12	12	]			
U/D to TC		13	13	16	16"	]			
CE to RC		10	10	11	11	<u> </u>			
Power Dissipation Capacitance	C <sub>PD</sub> *	59	55	78	68	pF			

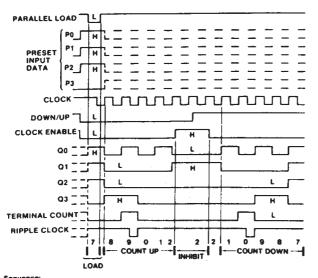
<sup>\*</sup>C<sub>PD</sub> is used to determine the power consumption, per package.

PD=C<sub>PD</sub> V<sub>Cc</sub><sup>2</sup> fi + ∑ (C<sub>L</sub> V<sub>Cc</sub><sup>2</sup> fo) where: f<sub>i</sub>=input frequency f<sub>o</sub>=output frequency C<sub>L</sub>=output load capacitance V<sub>Cc</sub>=supply voltage

SWITCHING CHARACTERISTICS (Ct = 50 pF, input tr, tf = 6 ns)

				25	°C	4	3	40°C t	o +85°	°C	-55°C to +125°C				
CHARACTERISTIC	SYMBOL	Voc	F	iC	Н	СТ	L 74	НС	741	1CT	54	НС	541	нст	UNIT
			Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	
Propagation Delay	tech	2		195	4			245	_	_	_	295	-	-	
PL to Qn	tpHL	4.5	_	39	1	40	_	49	_	50	_	59	-	60	
<u></u>		6	_	33	_	_		42	_			50			
	tрин	2		175	-	-	_	220	-	-		265	-	-	
Pn to Qn	t <sub>PHL</sub>	4.5	_	35	-	38		44		48	-	53	-	57	
		6	<del>  -  </del>	30				37		_		45			
25.	t <sub>PLH</sub>	2	-	170	_	_	_	215	_	_	_	255	_	_	
CP to Qn	tehr	4.5	-	34	_	35		43	_	44	_	51 43	-	53	
		6 2		29 125			_	37 155					_		
CP to RC	t <sub>PLH</sub> .	4.5	_	25	_	27	_	31	_	34	_	190 38		41	
CF to NC	t <sub>PHL</sub>	6		21	_		_	26	_	34		32		41	
	t <sub>PLH</sub>	2		210				265				315	=	$\equiv$	
CP to TC	teh	4.5	_	42		42		53	_	53		63	_	63	ns
3	NF FIL	6	_	36			_	45	_	_	_	54		_	,,,
	tpLH	2	_	150	_			190	_	_		225	_		
U/D to RC	tenc	4.5	_	30		30	_	38	_	38	_	45	_	45	
		6		26	_	_	_	33	_	-	_	38	_	_	
	tpLH	2	_	165	_	_	_	205	_	_	_	250	_	_	
U/D to TC	tpHL	4.5	_	33	_ ,	38	_	41	_	48		50		57	
		6		28			_	35		[		43			
	tpLH	2	-	125				155		-	-	190	-	-	
CE to RC	t <sub>PHL</sub>	4.5	-	25	_	27	_	31	-	34	-	38	-	41	
		6		21				26			_	32			
Output Transition	tтьн	2	_	75	_	-	-	95	-	-	-	110	-	-	
Time	t <sub>THL</sub>	4.5	_	15	_	15	-	19	-	19	-	22	-	22	
Qn, TC, RC		6		13				16			_	19	_		
Input Capacitance	Cı		_	.10	_	10		10		10	_	10	_	10	pF

#### **TIMING DIAGRAMS**



(1) Load (preset) to BCD seven

(3) Inhibit

(2) Count up to eight, nine, zero, one and two ! (4) Count down to one, zero, nine, eight, and sever

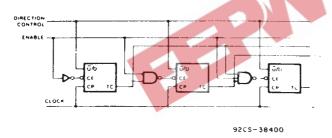
CLOCK DOWN/UP 2

(1) Load (preset) to binary thirteen

inhibit sequences.

(4) Count down to one, zero, fifteen fourteen, and thirteen

Fig. 4 - HC/HCT190 decade counters typical load, count, and



inhibit sequences.

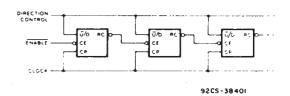
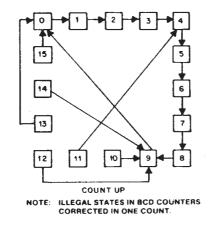
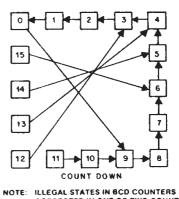


Fig. 5 - HC/HCT191 binary counters typical load, count, and

Fig. 6 - Sychronous n-stage counter with parallel gated Terminal Count.

Fig. 7 - Synchronous n-stage counter using ripple clock.

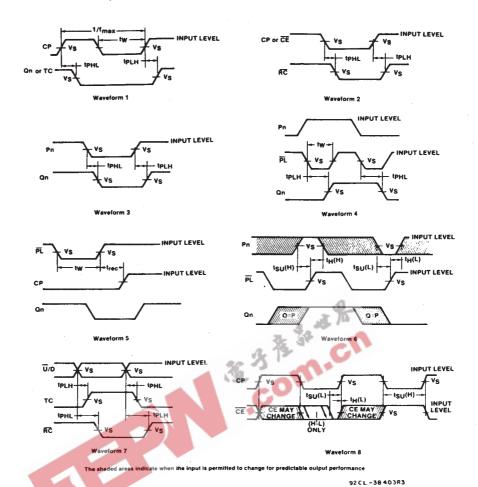




NOTE: ILLEGAL STATES IN BCD COUNTERS CORRECTED IN ONE OR TWO COUNTS.

92CM-40338

Fig. 8 - HC/HCT190 State Diagrams.



	54/74HC	54/74HCT
Input Level	VCC	3 V
Switching Voltage, VS	50% VCC	1.3 V

Fig. 9 - Transition, propagation delay, setup and hold, and recovery times.

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